

Thermoset Chip Glue (Red) - 10cc syringe



Product Highlights

Heat curing epoxy adhesive designed to bond surface mount chips and ICs to printed circuit boards (PCBs).

Allows large/heavy surface mount components to be permanently bonded to a PCB during reflow, allowing two-sided surface mount reflow without larger chips/ICs coming loose.

Specifications

Curing Time: 90 to 120 seconds at 150+ °C (302+ °F)
Designed to cure at leaded and lead free reflow temperatures.

Packaging: 30cc/30g Syringe

Shelf Life: Refrigerated >12 months, Unrefrigerated >12 months

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F)
>4 hours @ 50-70% RH 22-28°C (72-82°F)

Application

Apply by dot dispensing, line dispensing, or with stencil and squeegee.

Cleaning

Clean using isopropyl alcohol (IPA).

Storage and Handling

Store at 3-25°C (37-77°F). Do not freeze. Allow 4 hours for thermoset chip glue to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.